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Advances in Imaging-Based NDT Methods

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Message from the Guest Editor

This Special Issue's focus is on the advancements of imaging based non-destructive testing and evaluation (NDT&E) methods for inspection of various metals, semiconductors, composites and biomaterials. The main focus is given to widely used non-destructive testing and evaluation methodologies and associated data processing schemes for inspection of various industrial and biomaterials.

Topics of interest

This Special Issue on NDT&E focuses on both laboratory and field applications, including but not limited to the following:

- Ultrasonic Testing
- Radiographic Testing
- Thermographic Testing
- Optical Testing
- Eddy Current Testing
- Magnetic Particle Inspection
- Liquid Penetrant Examination
- Signal/Image/Video Processing techniques for improving the sensitivity and resolution for visualization of surface/subsurface/volumetric defects.
- Non-destructive Testing/Non-invasive Inspection of Biomaterials
- Data fusion for NDT&E.



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Special Issue